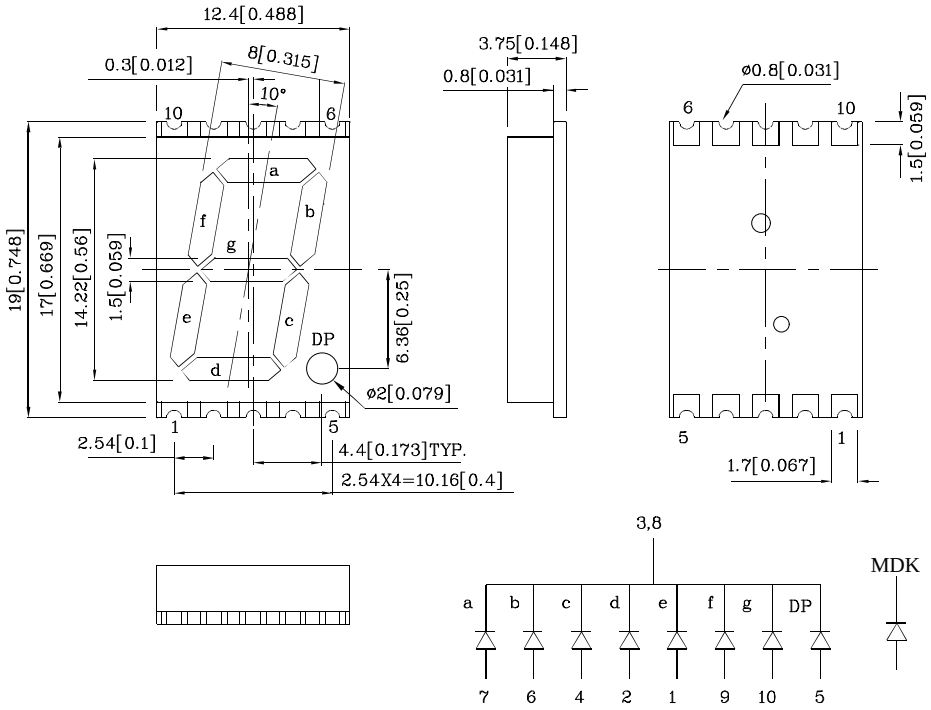
Part Number: XZFMDK14C

SURFACE MOUNT DISPLAY

Features

- 0.56 inch digit height
- Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 400pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS compliant

Package Schematics



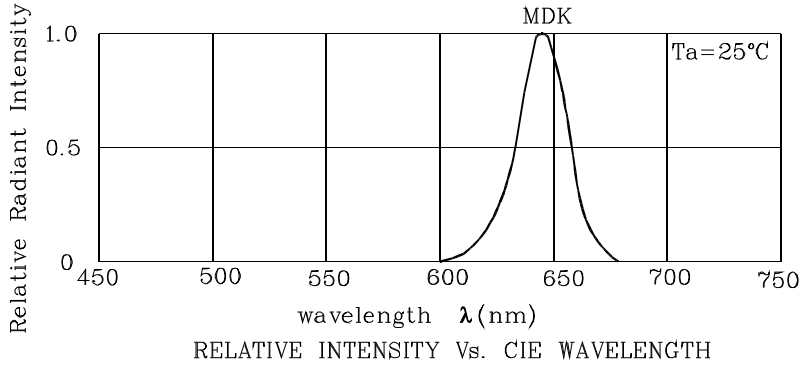
Notes:
1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
2. Specifications are subject to change without notice.
3.The gap between the reflector and PCB shall not exceed 0.25mm.

Absolute Maximum Ratings (T_A=25°C)		**MDK (AlGaInP)**	**Unit**
Reverse Voltage	V_R	5	V
Forward Current	I_F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	185	mA
Power Dissipation	P_D	75	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

Operating Characteristics (T_A=25°C)		**MDK (AlGaInP)**	**Unit**
Forward Voltage (Typ.) (I_F=10mA)	V_F	1.85	V
Forward Voltage (Max.) (I_F=10mA)	V_F	2.5	V
Reverse Current (Max.) (V_R=5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I_F=10mA)	λP	645*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I_F=10mA)	λD	630*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I_F=10mA)	△λ	28	nm
Capacitance (Typ.) (V_F=0V, f=1MHz)	C	35	pF

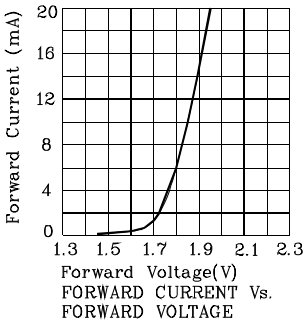
Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I_F=10mA) ucd		Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XZFMDK14C	Red	AlGaInP	21000 5600*	43990 13990*	645*	Common Cathode,Rt. Hand Decimal.

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

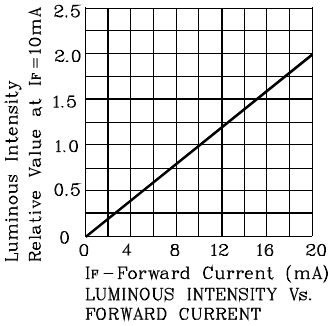


RELATIVE INTENSITY Vs. CIE WAVELENGTH

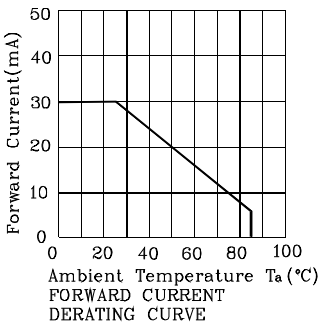
❖ MDK



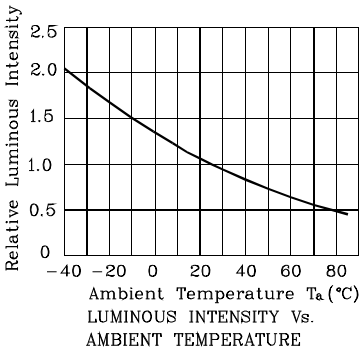
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT



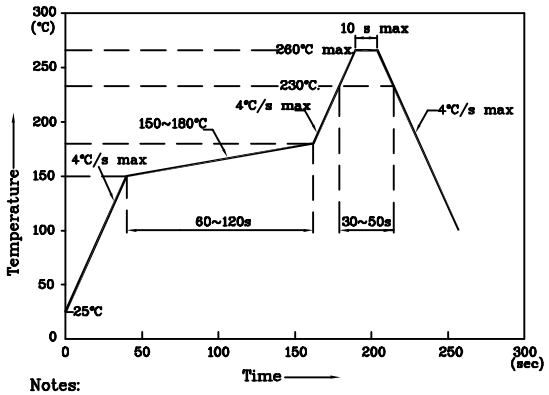
FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

LED is recommended for reflow soldering and soldering profile is shown below.

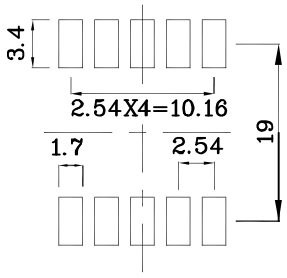
Reflow Soldering Profile for SMD Products (Pb–Free Components)



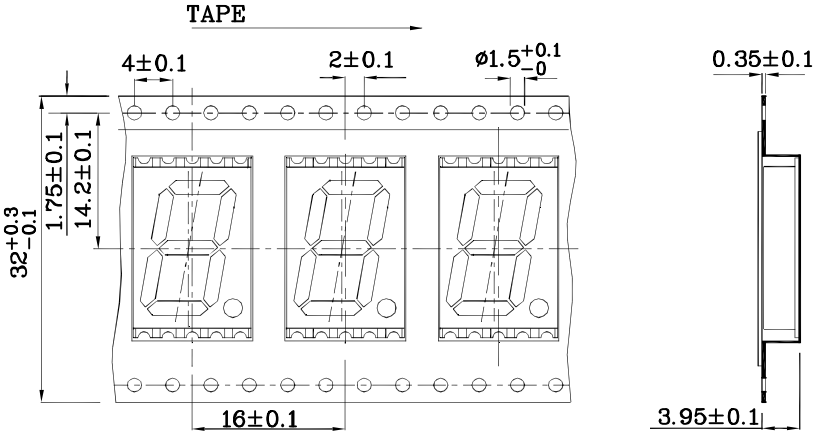
Notes:

1. **Maximum soldering temperature should not exceed 260°C**
2. **Recommended reflow temperature: 145°C–260°C**
3. **Do not put stress to the epoxy resin during high temperatures conditions**

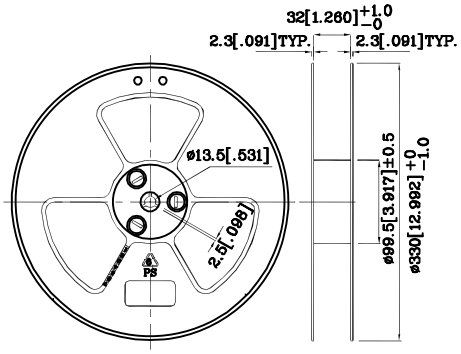
❖ Recommended Soldering Pattern (Units : mm; Tolerance: ±0.15)



❖ Tape Specification (Units : mm)

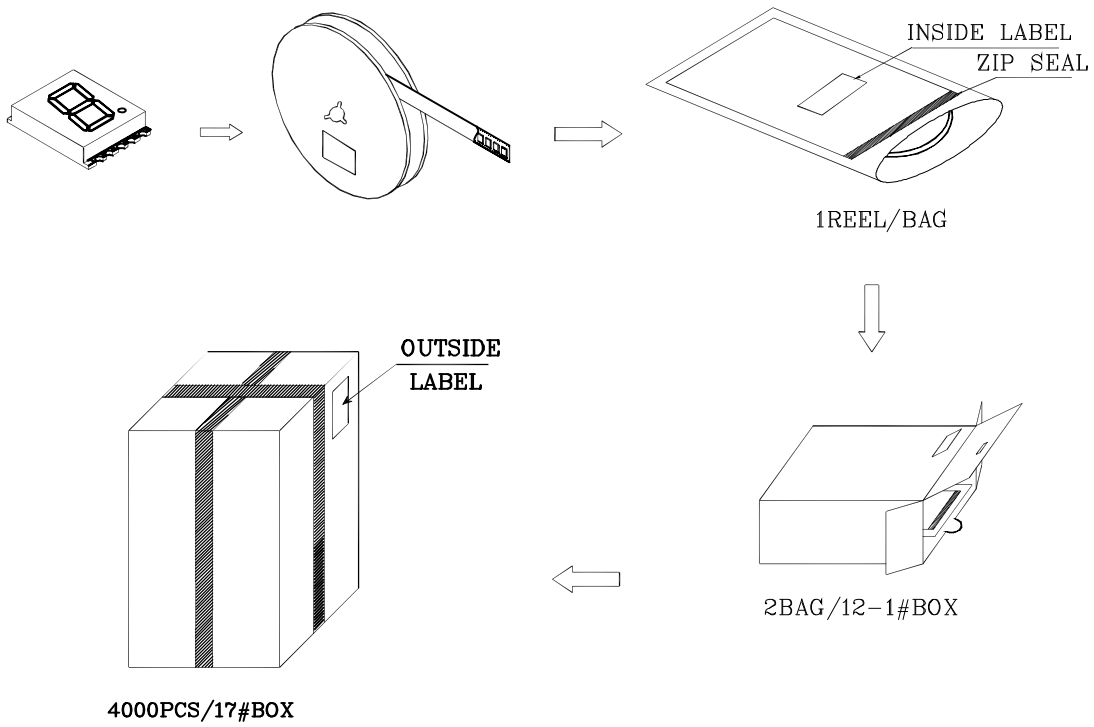


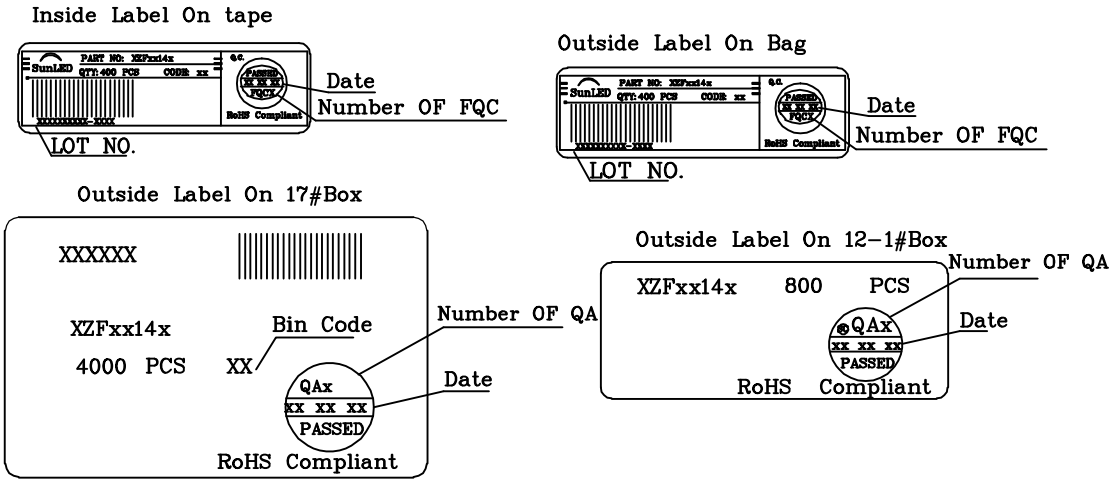
❖ Reel Dimension



Remarks:
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:
1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V
Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS





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